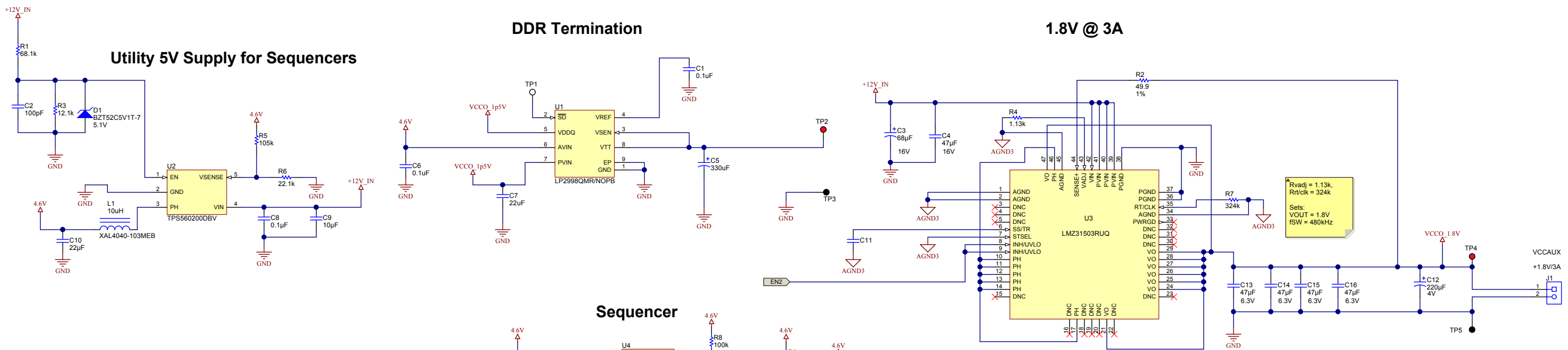
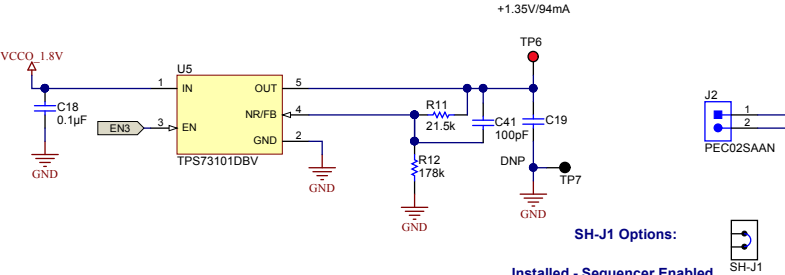


VCCAUX, VCCAUX\_IO, VCCO\_1.8V, MGTVCCAUX, VCCADC

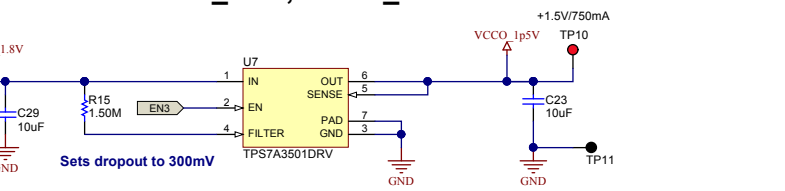
1.8V @ 3A



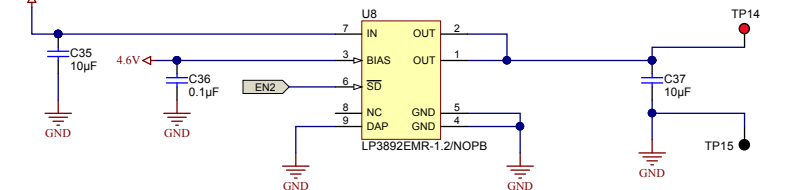
VCCO\_1.35V



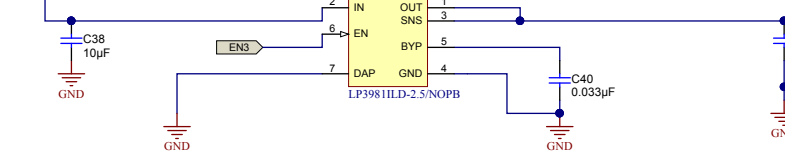
VCCO\_1.5V, VCCO\_DDR



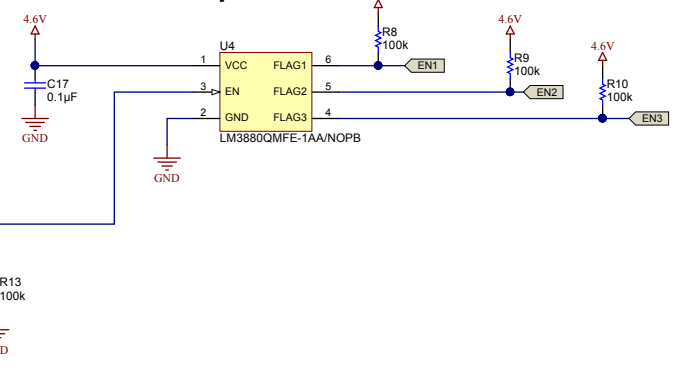
MGTAVTT, VCCO\_1.2V



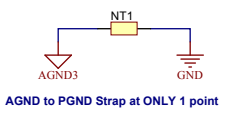
VCCO\_2.5V



Sequencer

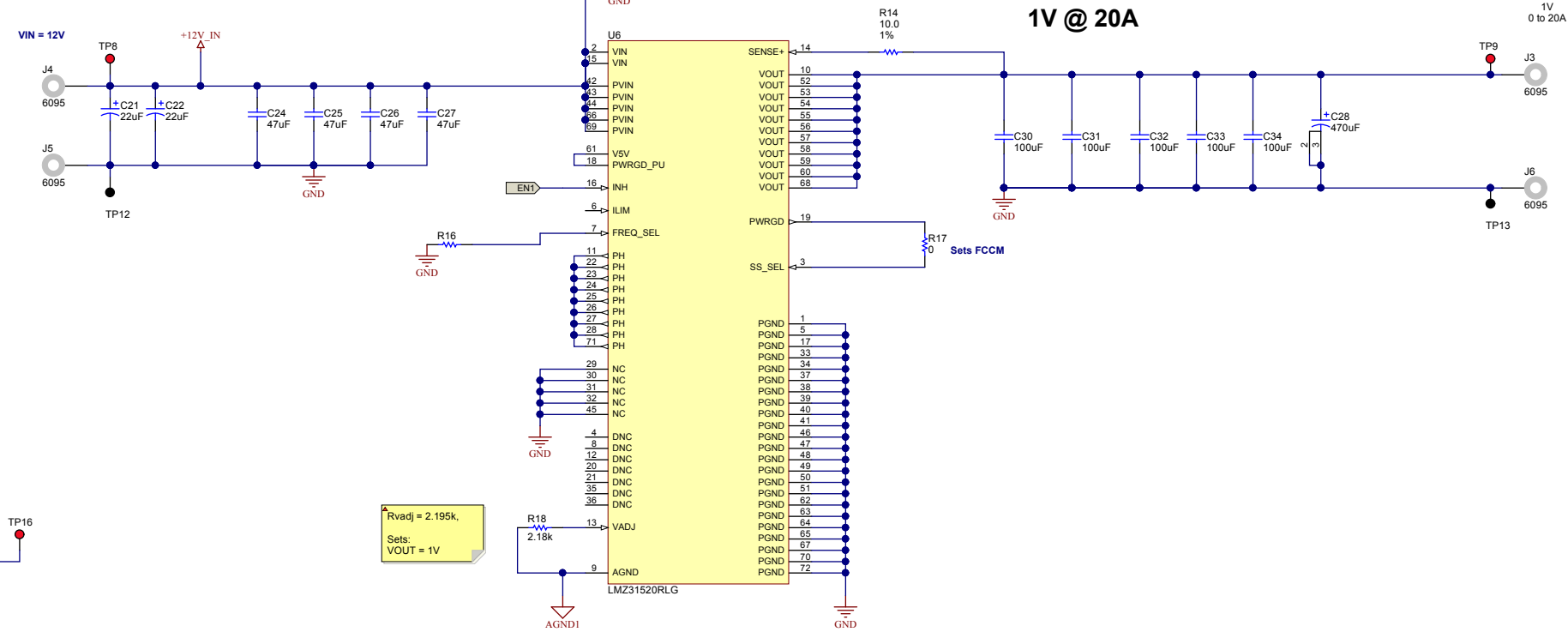


PH pins should be connected to a copper island under the device for thermal relief. DO NOT connect any external component or net to this pin.  
DO NOT connect AGNDs on this page to a common system AGND



VCCINT, VCCINT\_IO, VCCBRAM

1V @ 20A



AGND internally tied to PGND on LMZ3 series modules  
PH pins should be connected to a copper island under the device for thermal relief. DO NOT connect any external component or net to this pin.

Orderable: N/A	Designed for: Public Release	Mod. Date: 4/15/2015
TID #: PMP10613	Project Title: PMP10613	
Number: TIDA-10613	Rev: E1	Sheet Title:
Drawn By: Version control disabled	Assembly Variant: 001	Sheet: 1 of 2
Engineer: Frank Xiao	Contact: http://www.ti.com/support	Size: B

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H1 SJ-5303 (CLEAR) H2 SJ-5303 (CLEAR) H3 SJ-5303 (CLEAR) H4 SJ-5303 (CLEAR)

DNP FID1 DNP FID2 DNP FID3

PCB Number: TIDA-10613  
PCB Rev: E1

PCB  
LOGO  
Texas Instruments

LBL1  
PCB Label  
Size: 0.65" x 0.20 "

Label Table	
Variant	Label Text
001	ChangeMe!

ZZ2  
Assembly Note  
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3  
Assembly Note  
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4  
Assembly Note  
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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Designed for: <a href="#">Public Release</a>		Mod. Date: 4/15/2015	
Project Title: <a href="#">PMP10613</a>			
Number: <a href="#">TIDA-10613</a>		Rev: <a href="#">E1</a>	
SVN Rev: <a href="#">Version control disabled</a>		Assembly Variant: <a href="#">001</a>	
Drawn By: <a href="#">Frank Xiao</a>		Sheet: <a href="#">2</a> of <a href="#">2</a>	
Engineer: <a href="#">Frank Xiao</a>		File: <a href="#">Hardware ANSI-B.SchDoc</a>	
		Size: B	
		Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	



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